



HLT3000

Two-part, Dispensable Thermal Gap Filler with High Thermal Conductivity

BENEFIT AND FEATURES

- Modified viscosity and thixotropy properties
- Suitable for dispensing and printing process
- Thin bond line
- Excellent surface wetting
- Proven long term reliability

OVERVIEW

Honeywell HLT3000 is two-part, dispensable thermal gap filler with low viscosity and good thixotropy properties. The gap filler is silicone based, it is easy to dispense and print after 1:1 mixing. It is formulated to balance thermal performance, phase separation and long term reliability. With its high compressibility, it is designed to minimize thermal resistance at interfaces and suitable for thin bond line applications. The material is available in 200+200cc syringes, 1+1 gallon and 5+5 gallon jars.

TYPICAL APPLICATIONS

- EV battery package
- Automotive electronics
- Telecommunications
- LED lighting
- Consumer electronics

STORAGE & USE

- Shelf Life 6 months at 23±2°C

Property		HLT3000	Test Method
Specific Gravity		3.1	ASTM D792
Viscosity (cps@25°C)		100,000-200,000	ASTM D2196 (Brookfield Viscometer, #7 spindle, 10rpm)
Hardness (Shore00)		50	ASTM D2240
Thermal Conductivity (W/m-K)		3.0	ASTM D5470
Dielectric Strength (KV/mm)		>10	ASTM D149
Volume Resistivity(Ω -cm)		>1.0×10 ¹³	ASTM D257
BLT(mm)		0.05	-
Cure Schedule	25°C (hr)	18	-
	120°C (min)	20	-
Pot Life	25°C (min)	>60	-
Color		White/Blue	Visual

Honeywell Electronic Materials

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